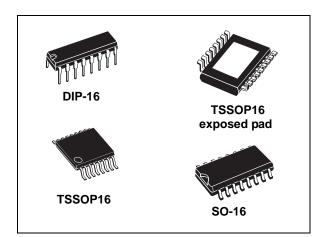
STP08CP05



Low voltage, low current power 8-bit shift register

Datasheet - production data



Features

- · Low voltage power supply down to 3 V
- 8 constant current output channels
- Adjustable output current through external resistor
- Serial data IN/parallel data OUT
- 3.3 V micro driver-able
- Output current: 5-100 mA
- 30 MHz clock frequency
- Available in high thermal efficiency TSSOP exposed pad
- ESD protection 2.5 kV HBM, 200 V MM

Description

The STP08CP05 is a monolithic, low voltage, low current, power 8-bit shift register designed for LED panel displays. The STP08CP05 contains an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. In the output stage, eight regulated current sources were designed to provide 5-100 mA constant current to drive the LEDs, the output current setup time is 11 ns (typ), thus improving the system performance.

The STP08CP05 is backward compatible in functionality and footprint with STP8C/L596. Through an external resistor, users can adjust the STP08CP05 output current, controlling in this way the light intensity of LEDs, in addition, user can adjust LED's brightness intensity from 0% to 100% via $\overline{\text{OE}}$ pin.

The STP08CP05 guarantees a 20 V output driving capability, allowing users to connect more LEDs in series. The high clock frequency, 30 MHz, also satisfies the system requirement of high volume data transmission. The 3.3 V of voltage supply is useful for applications that interface with any micro from 3.3 V. Compared with a standard TSSOP package, the TSSOP exposed pad increases heat dissipation capability by a 2.5 factor.

Table 1. Device summary

Order codes	Package	Packaging
STP08CP05B1R	DIP-16	25 parts per tube
STP08CP05MTR	STP08CP05MTR SO-16 (Tape and reel)	
STP08CP05TTR	STP08CP05TTR TSSOP16 (Tape and reel)	
STP08CP05XTTR	TSSOP16 exposed pad (Tape and reel)	2500 parts per reel

Contents

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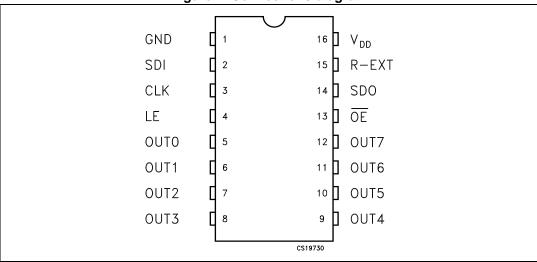
1 Summary description

Table 2. Typical current accuracy

Output voltage	Current a	Output current	
Output voltage	Between bits	Between ICs	Output current
≥ 1.3 V	± 1.5%	± 3%	20 to 100 mA

1.1 Pin connection and description

Figure 1. Connections diagram



Note:

The exposed pad should be electrically connected to a metal land electrically isolated or connected to ground.

Table 3. Pin description

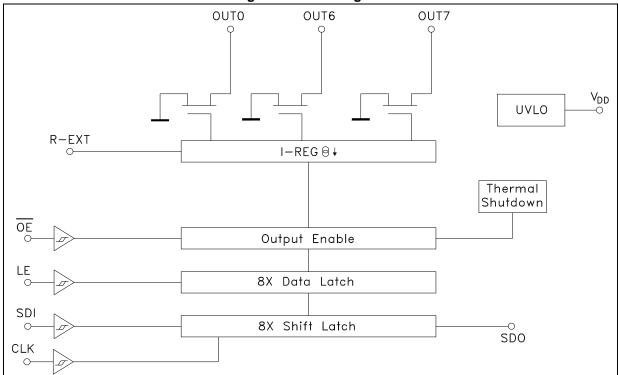
Pin N°	Symbol	Name and function		
1	GND	Ground terminal		
2	SDI	Serial data input terminal		
3	CLK	Clock input terminal		
4	LE	Latch input terminal		
5-12	OUT 0-7	Output terminal		
13	ŌĒ	Output enable input terminal (active low)		
14	SDO	Serial data out terminal		
15	R-EXT	Constant current programming		
16	V_{DD}	5 V supply voltage terminal		



Block diagram STP08CP05

2 Block diagram

Figure 2. Block diagram



4

STP08CP05 Maximum rating

3 Maximum rating

Stressing the device above the rating listed in the "absolute maximum ratings" table may cause permanent damage to the device. these are stress ratings only and operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

3.1 Absolute maximum ratings

Table 4. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DD}	Supply voltage I _{GND}	0 to 7	V
Vo	Output voltage	-0.5 to 20	V
Io	Output current	100	mA
I _{GND}	GND terminal current	800	mA
f _{CLK}	Clock frequency	50	MHz
T _{OPR}	Operating temperature range	-40 to +125	°C
T _{STG}	Storage temperature range	-55 to +150	°C

3.2 Thermal data

Table 5. Thermal data

Symbol	Parameter	DIP-16	SO-16	TSSOP16	TSSOP16 ⁽¹⁾ exposed pad	Unit
R_{thJA}	Thermal resistance junction-ambient	90	125	140	37.5	°C/W

^{1.} The exposed-pad should be soldered to the PBC to realize the thermal benefits

Maximum rating STP08CP05

3.3 Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Test conditions	Min	Тур	Max	Unit
V_{DD}	Supply voltage		3.0		5.5	V
Vo	Output voltage				20	V
Io	Output current	OUTn	5		100	mA
I _{OH}	Output current	SERIAL-OUT			+1	mA
I _{OL}	Output current	SERIAL-OUT			-1	mA
V _{IH}	Input voltage		0.7 V _{DD}		V _{DD} +0.3	V
V _{IL}	Input voltage		-0.3		0.3 V _{DD}	V
t _{wLAT}	LE pulse width		20			ns
t _{wCLK}	CLK pulse width		20			ns
t _{wEN}	OE pulse width	V _{DD} = 3.0 to 5.0 V	200			ns
t _{SETUP(D)}	Setup time for DATA	V _{DD} = 3.0 to 3.0 V	7			ns
t _{HOLD(D)}	Hold time for DATA		4			ns
t _{SETUP(L)}	Setup time for LATCH		15			ns
f _{CLK}	Clock frequency	Cascade operation (1)			30	MHz

^{1.} In order to achieve high cascade data transfer, please consider $t_{\rm r}/t_{\rm f}$ timings carefully.

4 Electrical characteristics

 V_{DD} = 3.3 V to 5 V, T = 25 °C, unless otherwise specified.

Table 7. Electrical characteristics

Symbol	Parameter	Test conditions	Min	Тур	Max	Unit
V_{IH}	Input voltage high level		0.7 V _{DD}		V_{DD}	V
V _{IL}	Input voltage low level		GND		0.3V _{DD}	V
I _{OH}	Output leakage current	V _{OH} = 20 V		0.5	10	μА
V _{OL}	Output voltage (Serial-OUT)	I _{OL} = 1 mA		0.03	0.4	V
V _{OH}	Output voltage (Serial-OUT)	I _{OH} = -1 mA	V _{OH} - V _{DD} =- 0.4 V			V
I _{OL1}		$V_{O} = 0.3 \text{ V}, R_{ext} = 3.9 \text{ k}\Omega$	4.25	5	5.75	
I _{OL2}	Output current	$V_{O} = 0.3 \text{ V}, R_{ext} = 970 \Omega$	19.4	20	20.6	mA
I _{OL3}		$V_{O} = 1.3 \text{ V}, R_{ext} = 190 \Omega$	97	100	103	
Δl _{OL1}	Output current error	$V_{O} = 0.3 \text{ VR}_{EXT} = 3.9 \text{ k}\Omega$		± 5	± 8	
Δl _{OL2}	between bit	$V_{O} = 0.3 \text{ VR}_{EXT} = 970 \Omega$		± 1.5	± 2.75	%
Δl _{OL3}	(All Output ON)	$V_0 = 1.3 \text{ VR}_{EXT} = 190 \Omega$		± 1.2	± 2.5	
R _{SIN(up)}	Pull-up resistor		150	300	600	ΚΩ
R _{SIN(down)}	Pull-down resistor		100	200	400	ΚΩ
I _{DD(OFF1)}	Supply current (OFF)	R _{EXT} = 980 OUT 0 to 7 = OFF		4	5	
I _{DD(OFF2)}	Зарріу сапені (ОГГ)	R _{EXT} = 250 OUT 0 to 7 = OFF		11.2	13.5	m ^
I _{DD(ON1)}	Supply current (ON)	R _{EXT} = 980 OUT 0 to 7 = ON		4.5	5	mA
I _{DD(ON2)}	- Зарріу сипепі (ОМ)	R _{EXT} = 250 OUT 0 to 7 = ON		11.7	13.5	
Thermal	Thermal protection (1)			170		°C

Guaranteed by design (not tested)
 The thermal protection switches OFF only the outputs



5 Switching characteristics

 V_{DD} = 5 V, T = 25 °C, unless otherwise specified.

Table 8. Switching characteristics

Symbol	Parameter	Test conditions			Min	Тур	Max	Unit
t	Propagation delay time, CLK-OUTn, LE = H,			$V_{DD} = 3.3 \text{ V}$		35	50	ns
t _{PLH1}	OE = L			$V_{DD} = 5 V$		18	28	113
4	Propagation delay time, LE -OUTn,			$V_{DD} = 3.3 \text{ V}$		48	74	no
t _{PLH2}	OE = L			$V_{DD} = 5 V$		30	50	ns
	Propagation delay time,			V _{DD} = 3.3 V		55	82	
t _{PLH3}	OE -OUTn, LE = H			V _{DD} = 5 V		37	58	ns
touu	Propagation delay time,			V _{DD} = 3.3 V		21	28	ns
t _{PLH}	CLK-SDO			$V_{DD} = 5 V$		17	22	113
	Propagation delay time, CLK-OUTn, LE = H,	\/ - 2 2 \/	$V_{DD} = 3.3 \text{ V}$ $V_{IH} = V_{DD}$ $V_{IL} = GND$ $C_L = 10 \text{ pF}$	$V_{DD} = 3.3 \text{ V}$		11	17	ns
t _{PHL1}	OE = L	$V_{DD} = 3.3 V$ $V_{IL} = GND$		$V_{DD} = 5 V$		7	11	115
4	Propagation delay time, LE -OUTn,	$I_0 = 20 \text{ mA}$	_	$V_{DD} = 3.3 \text{ V}$		24	40	no
t _{PHL2}	OE = L	KEXT = 1 K22	$EXT = 1 \text{ K}\Omega$ $R_L = 60 \Omega$	$V_{DD} = 5 V$		21	31	ns
	Propagation delay time,			V _{DD} = 3.3 V		20	35	
t _{PHL3}	OE -OUTn, LE = H			V _{DD} = 5 V		18	28	ns
t	Propagation delay time,			V _{DD} = 3.3 V		24	32	ns
t _{PHL}	CLK-SDO			$V_{DD} = 5 V$		19	25	113
	Output fall time			$V_{DD} = 3.3 \text{ V}$		26	40	no
t _{ON}	10~90% of voltage waveform			V _{DD} = 5 V		11	17	ns
	Output rise time			V _{DD} = 3.3 V		5	10	
t _{OFF}	90~10% of voltage waveform			V _{DD} = 5 V		4	8	ns
t _r	CLK rise time (1)						5000	ns
t _f	CLK fall time (1)						5000	ns

^{1.} In order to achieve high cascade data transfer, please consider tr/tf timings carefully.

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6 Equivalent circuit and outputs

Figure 3. OE terminal

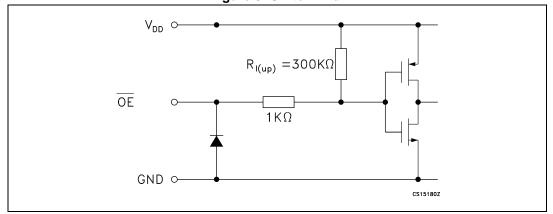


Figure 4. LE terminal

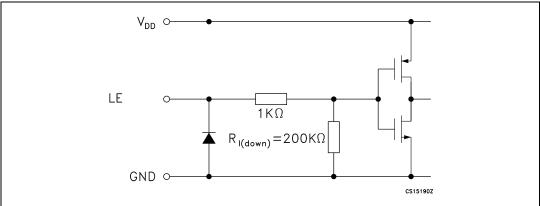


Figure 5. CLK, SDI terminal

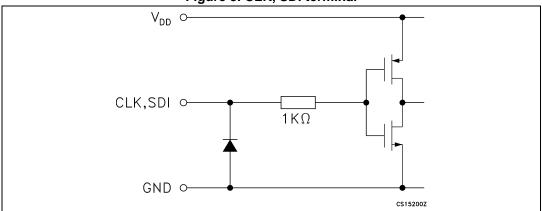
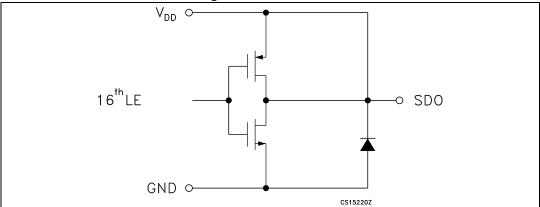


Figure 6. SDO terminal



7 Truth table and timing diagram

7.1 Truth table

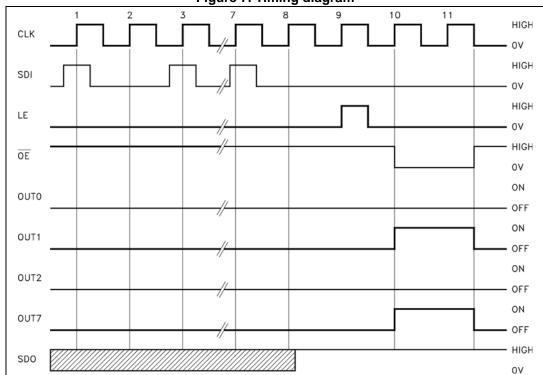
Table 9. Truth table

Clock	LE	ŌĒ	SDI	SDI <u>OUT0</u> <u>OUT0</u> <u>OUT7</u>	
	Н	L	Dn	Dn Dn -5 Dn -7	Dn -7
_ _ _	L	L	Dn + 1	No change	Dn -7
_ _ _	Н	L	Dn + 2	Dn +2 Dn -3 Dn -5	Dn -5
	Х	L	Dn + 3	Dn +2 Dn -3 Dn -5	Dn -5
	Х	Н	Dn + 3	OFF	Dn -5

Note: OUT0 to OUT7 = ON when Dn = H; OUT0 to OUT7 = OFF when Dn = L.

7.2 Timing diagram

Figure 7. Timing diagram



 t_{WCLK} 50% 50% CLK $\dagger_{\mathsf{SETUP}(\mathsf{D})}$ SDI 50% 50% †_{HOLD(D)} SDO 50% t_{PLH} /t_{PHL}

Figure 8. Clock, serial-in, serial-out



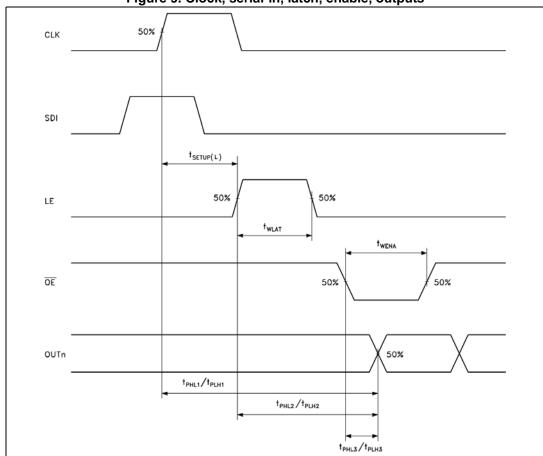
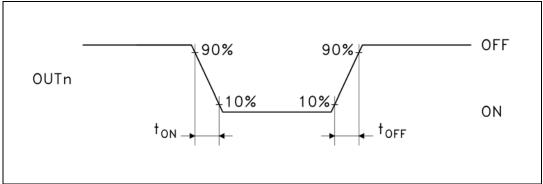


Figure 10. Outputs





Note:

8 Typical characteristics

Figure 11. Output current-R_{EXT} resistor

8000
7000
6000
4000
3000
2000
1000
0 10 20 30 40 50 60 70 80 90 100 110 120 130 140
Ouput Current (mA)

Table 10. Output current-R_{EXT} resistor

 $T_A = 25$ °C, Iset = 3 mA; 5 mA; 10 mA; 20 mA; 50 mA; 80 mA; Max

Output current (mA)	3	5	10	20	50	80	130	
Rext (Ω)	6740	3930	1913	963	386	241	124	

Maximum output current capabilities setting was 130 mA applying an Rext = 124 Ω .



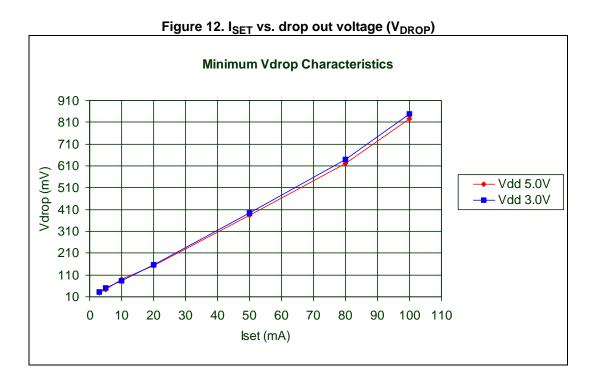


Table 11. I_{SET} vs drop out voltage (V_{DROP})

Vdd (V)	Iset (mA)	Rext (Ω)	Vdrop min (mV)	Vdrop max (mV)	Vdrop AVG (mV)
	3	6470	30.6	31.2	30.93
	5	3930	46.5	52.9	48.63
	10	1910	80.9	100	82.26
3	20	963	150	161	157
	50	386	392	396	394.3
	80	241	636	646	640.3
	100	192	846	850	848
	3	6470	25.6	29	26.96
	5	3930	40.8	41.7	41.16
	10	1910	80.1	105	89.2
5	20	963	153	154	154
	50	386	379	386	382
	80	241	618	626	621
	100	192	825	830	827



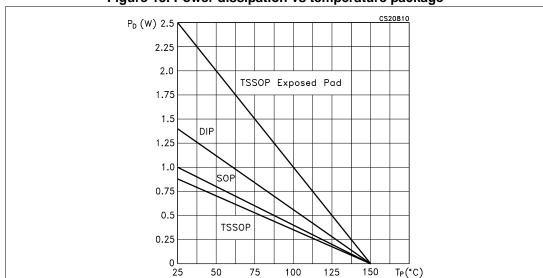
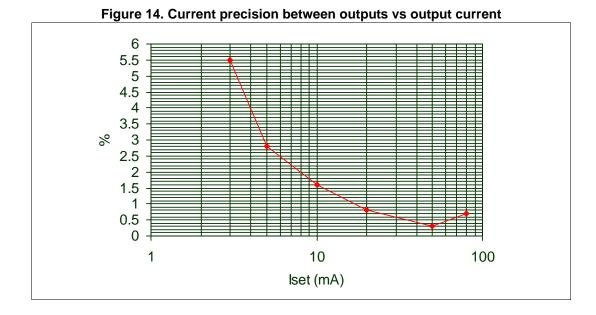


Figure 13. Power dissipation vs temperature package

Note:

The exposed-pad should be soldered to the PBC to realize the thermal benefits.



STP08CP05 Test circuit

9 Test circuit

Figure 15. DC characteristics

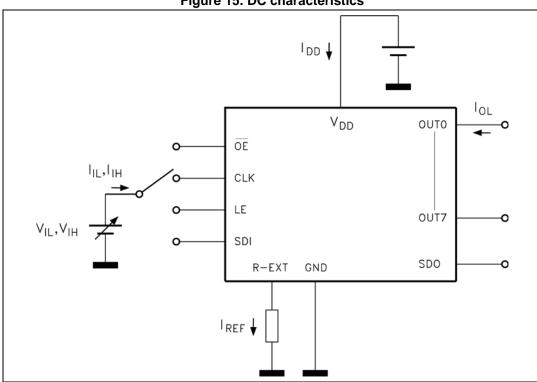
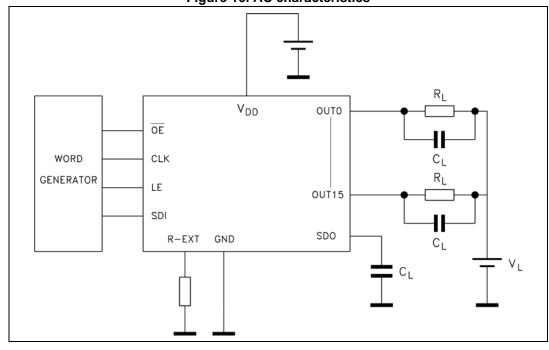


Figure 16. AC characteristics



10 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.



Table 12. DIP-16 mechanical data

Dim.	mm		
	Min.	Тур.	Max.
a1	0.51		
В	0.77		1.65
b		0.5	
b1		0.25	
D			20
E		8.5	
е		2.54	
e3		17.78	
F			7.1
I			5.1
L		3.3	
Z			1.27

Figure 17. DIP-16 drawing

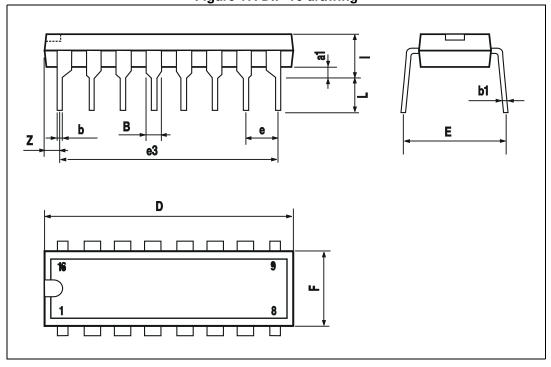




Table 13. TSSOP16 exposed pad mechanical data

Dim.	mm		
	Min.	Тур.	Max.
А			1.20
A1			0.15
A2	0.80	1.00	1.05
b	0.19		0.30
С	0.09		0.20
D	4.90	5.00	5.10
D1		3.00	
E	6.20	6.40	6.60
E1	4.30	4.40	4.50
E2		3.00	
е		0.65	
L	0.45	0.60	0.75
L1		1.00	
k	0.00		8.00
aaa			0.10

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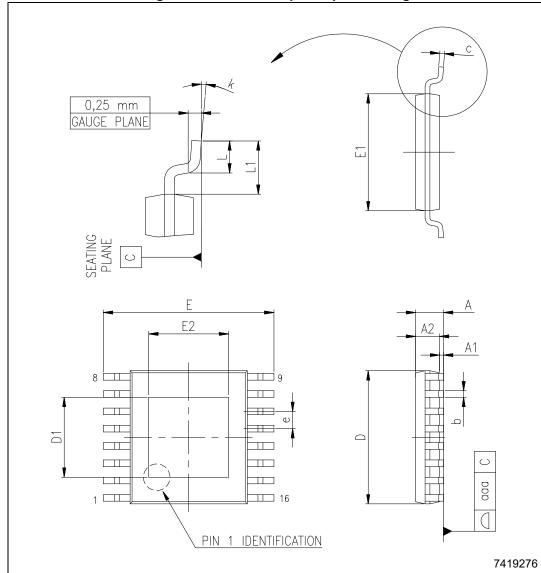


Figure 18. TSSOP16 exposed pad drawing

Table 14. TSSOP16 mechanical data

Dim.	mm		
	Min.	Тур.	Max.
А			1.20
A1	0.05		0.15
A2	0.80	1.00	1.05
b	0.19		0.30
С	0.09		0.20
D	4.90	5.00	5.10
Е	6.20	6.40	6.60
E1	4.30	4.40	4.50
е		0.65	
L	0.45	0.60	0.75
L1		1.00	
k	0		8
aaa			0.10

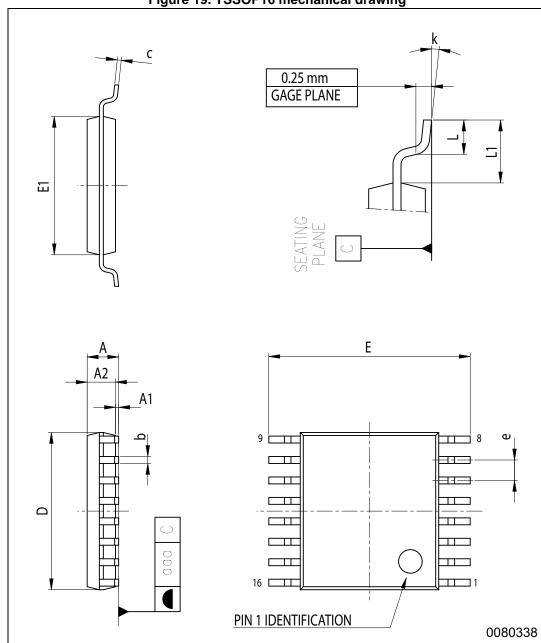


Figure 19. TSSOP16 mechanical drawing

Table 15. SO-16 dimensions

Dim.	mm		
	Min.	Тур.	Max.
Α			1.75
A1	0.10		0.25
A2	1.25		
b	0.31		0.51
С	0.17		0.25
D	9.80	9.90	10.00
Е	5.80	6.00	6.20
E1	3.80	3.90	4.00
е		1.27	
h	0.25		0.50
L	0.40		1.27
k	0		8°
ccc			0.10

С SEATING PLANE 0,25 mm GAGE PLANE С Ε Α2 Ε1 Α1 0 = ∞ Φ 222 9 = 0016020_F

Figure 20. SO-16 package drawing

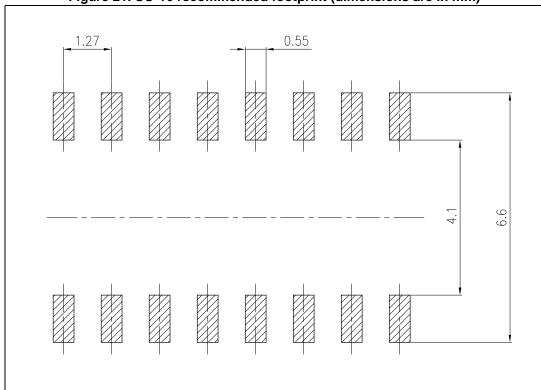


Figure 21. SO-16 recommended footprint (dimensions are in mm)

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11 Packaging mechanical data

Table 16. TSSOP16 exposed pad and TSSOP16 tape and reel mechanical data

Dim.	mm		
	Min.	Тур.	Max.
А			330
С	12.8		13.2
D	20.2		
N	60		
Т			22.4
Ao	6.7		6.9
Во	5.3		5.5
Ко	1.6		1.8
Po	3.9		4.1
Р	7.9		8.1



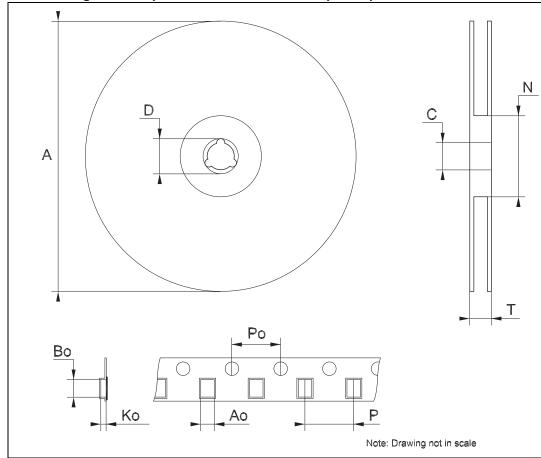


Figure 22. Tape and reel for TSSOP16 exposed pad and TSSOP16

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STP08CP05 Revision history

12 Revision history

Table 17. Document revision history

Date	Revision	Changes
23-May-2007	1	First release
28-Jun-2007	2	Updated Table 7 on page 7
12-Mar-2008	3	Updated Table 8 on page 8 and added Figure 11 and Figure 12 on page 15
07-Aug-2008	4	Updated Section 8: Typical characteristics on page 14
27-Aug-2010	5	Updated Note: on page 3
10-Jul-2013	6	Updated Section 10: Package mechanical data, Figure 3: OE terminal and Figure 4: LE terminal Added Section 11: Packaging mechanical data
28-Jun-2018	7	Updated: Table 14: TSSOP16 mechanical data and Figure 20: TSSOP16 mechanical drawing
29-Aug-2018	8	Updated: Figure 7: Timing diagram, Figure 8: Clock, serial- in, serial-out, Figure 9: Clock, serial-in, latch, enable, outputs, Figure 10: Outputs, Figure 15: DC characteristics and Figure 16: AC characteristics. Minor text changes.

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